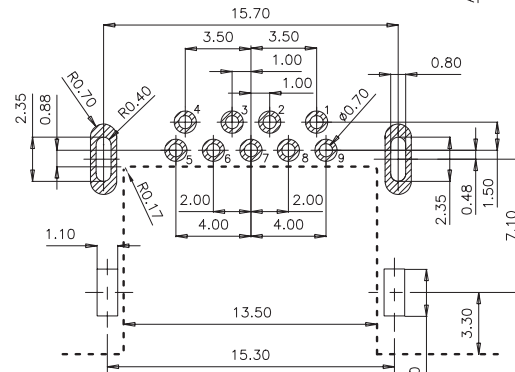
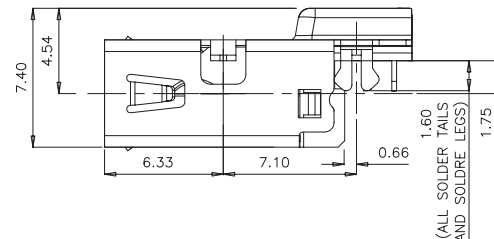
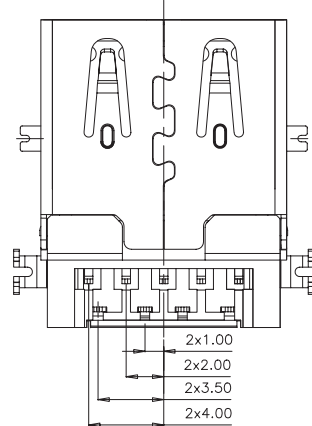
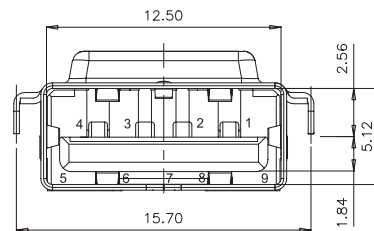
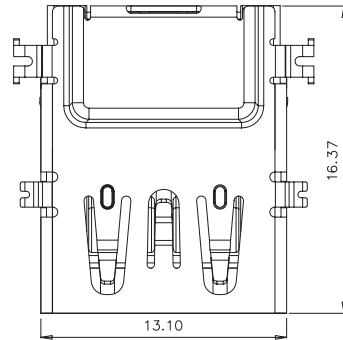




PCB LAYOUT * - COMPONENT VIEW

TECHNICAL CHARACTERISTICS

MATERIAL

INSULATOR: LCP

FLAMABILITY RATING: UL94-V0

COLOR: BLUE

CONTACT MATERIAL: PHOSPHORE BRONZE

CONTACT TYPE: STAMPED

CONTACT PLATING: UNDERPLATE 1.27 to 2.54 μm Ni

CONTACT AREA 0.76 μm Gold

SOLDER TAIL AREA 2.54 to 5.08 μm Matt Tin

SHIELDING: BRASS MATT TIN PLATED

ENVIRONMENTAL

OPERATING TEMPERATURE: -20 up to +85°C

COMPLIANCE: RoHS & LEAD FREE AS PER DIRECTIVE 2002/95/EC

HALOGEN FREE COMPLIANT AS PER IEC 61249-2-21

ELECTRICAL

CURRENT RATING:

- PIN 1 & PIN 4 (Vbus & corresponding ground PIN) 1.8A Max

- OTHER PINS 0.25 A Max

WORKING VOLTAGE: 30Vac

DIELECTRIC WITHSTANDING VOLTAGE: 100Vac/min

INSULATION RESISTANCE: > 100M Ω

CONTACT RESISTANCE:

- PIN 1 & PIN 4: 30m Ω Max

- OTHER PINS: 50m Ω Max

STANDARD

 CERTIFIED: E323964 / MODEL NUMBER 692121330100

MECHANICAL

INSERTION FORCE: 35.0N Max

EXTRACTION FORCE: 10.0N min

QUALITY CLASS: 5000 MATING CYCLES

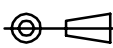
SOLDERING

WAVE PROCESS AS PER JEDEC J-STD-020D

PACKAGING

TAPE & REEL

* NOTE: THE RECOMMENDED PCB LAYOUT IS FOR AN OPTIMIZED RETENTION FORCE OF CONNECTOR ON PCB BUT IT IMPLIES INSERTION FORCE THAT A LOT OF PICK AND PLACE MACHINES ARE NOT ABLE TO HANDLE. THEREFORE IT MIGHT BE NECESSARY TO DRILL BIGGER HOLES FOR THE CLIPS. PLEASE CHECK THIS CAREFULLY.

RoHS Compliant									
G	01-APR-14	SOLDERING	QL	PROJECTION: 	GENERAL TOLERANCE	 WÜRTH ELEKTRONIK		SIZE	
F	12-AUG-13	DWG & CHARAC	QL						.X = +/- 0.2
E	09-NOV-11	STENCIL	GG		.XX = +/- 0.15				
D	21-SEP-11	NOTE	GG						
C	10-MAY-11	UL	GG	APPROVAL: RJ	UNIT: MM	DESCRIPTION: USB 3.0 REVERSE HORIZONTAL TYPE A WITH OFFSET 1.75 MM	A4		
B	02-MAY-11	DIMENSION	GG		SCALE:				
A	04-AUG-10	PDF	JP		SHEET: 1/3	WERI PART NO: 692 121 330 100			
REV	DATE	FILE	BY		DRAW: JOE				

